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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2826

Applicant: Paul A. Farrar

Title: HYDROPHOBIC FOAMED INSULATORS FOR HIGH DENSITY CIRCUITS

Docket No.: 303.610US1

Filed: August 25, 1999

Examiner: Fetsum Abraham

Customer No.: 21186



Serial No.: 09/382524

Due Date: January 22, 2004

Group Art Unit: 2826

Confirmation No.: 5340

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ A Response Under 1.111 (4 Pages).
- ☒ An Interview Summary (1 pg.).
- ☒ A Communication Concerning Related Applications (2 pgs.).
- ☒ A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 1 cited documents.

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

By: David R. Cochran
Atty: David R. Cochran
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O.Box 1450, Alexandria, VA 22313-1450, on this 17 day of December, 2003.

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S/N 09/382524

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar Examiner: Fetsum Abraham
Serial No.: 09/382524 Group Art Unit: 2826
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Title: HYDROPHOBIC FOAMED INSULATORS FOR HIGH DENSITY CIRCUITS

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/382929	August 25, 1999	303.603US1	PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES
09/503278 6413827	February 14, 2000	303.605US1	LOW DIELECTRIC CONSTANT SHALLOW TRENCH ISOLATION
10/184321	June 27, 2002	303.605US2	LOW DIELECTRIC CONSTANT SHALLOW TRENCH ISOLATION
10/184601	June 27, 2002	303.605US3	LOW DIELECTRIC CONSTANT SHALLOW TRENCH ISOLATION
10/184590	June 27, 2002	303.605US4	LOW DIELECTRIC CONSTANT SHALLOW TRENCH ISOLATION
10/184592	June 27, 2002	303.605US5	LOW DIELECTRIC CONSTANT SHALLOW TRENCH ISOLATION
09/507964	February 22, 2000	303.681US1	POLYNORBORNENE FOAM INSULATION FOR INTEGRATED CIRCUITS
10/099169	March 13, 2002	1303.041US1	LOW DIELECTRIC CONSTANT STI WITH SOI DEVICES



COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 09/382524

Filing Date: August 25, 1999

Title: HYDROPHOBIC FOAMED INSULATORS FOR HIGH DENSITY CIRCUITS

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10/179110	June 24, 2002	303.610US2	INSULATORS FOR HIGH DENSITY CIRCUITS
10/179091	June 24, 2002	303.610US3	A MEMORY SYSTEM WITH CONDUCTIVE STRUCTURES EMBEDDED IN FOAMED INSULATOR
10/179151	June 24, 2002	303.610US4	INSULATORS FOR HIGH DENSITY CIRCUITS
10/435171	May 8, 2003	303.605US6	LOW DIELECTRIC CONSTANT SHALLOW TRENCH ISOLATION

Respectfully submitted,

PAUL A. FARRAR

By Applicant's Representatives,

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Date 17 December 2003 By David R. Cochran
Reg. No. 46,632

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Name

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